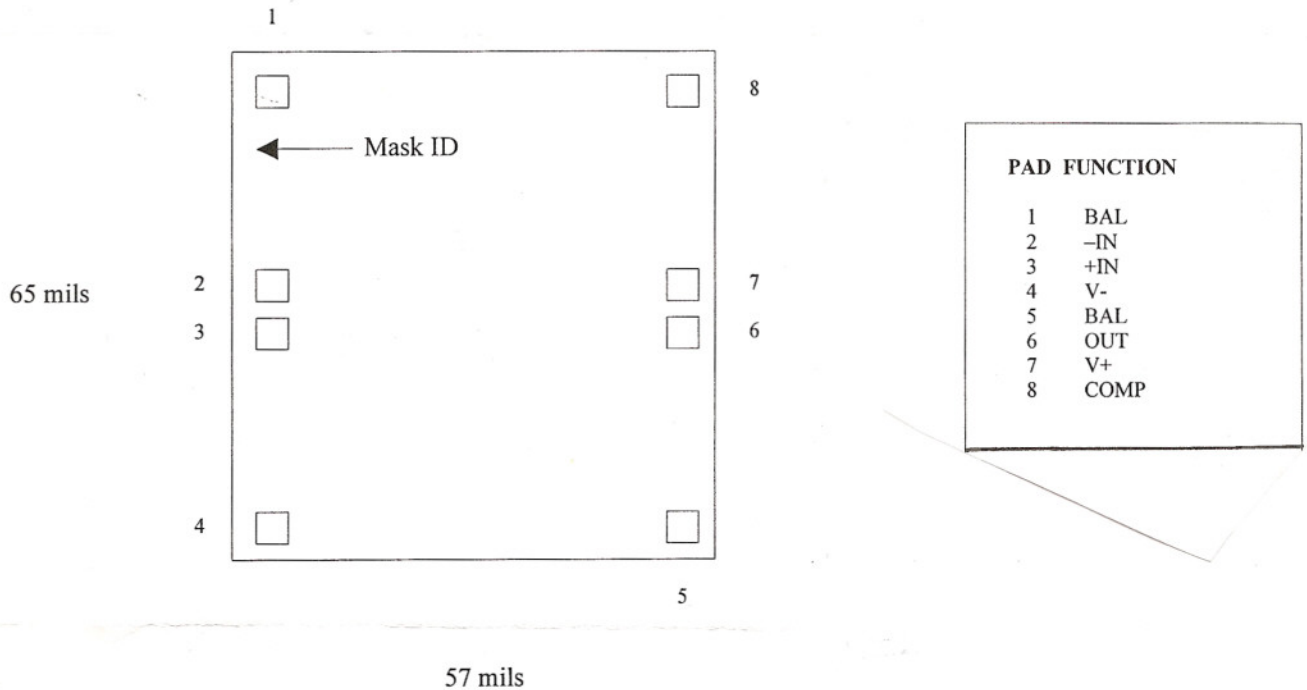




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



NOTE: Substrate must be unbiased.

Topside Metal: Aluminum
Backside Metal: Silliicon
Backside Potential: See Note
Bond Pad Size: .004" min.
Mask Ref:

APPROVED BY: J Kidd

DIE SIZE : .057" X .065"

DATE: 1/9/08

MFG: Harris

THICKNESS: .019"

Part # HA0-2525